

PATENT ABSTRACTS OF JAPAN

(11)Publication number : 2000-199863

(43)Date of publication of application : 18.07.2000

(51)Int.Cl.

G02B 23/24
H04N 5/225
// A61B 1/04
H04N 7/18

(21)Application number : 11-002094

(71)Applicant : SONY CORP

(22)Date of filing : 07.01.1999

(72)Inventor : MIYASHITA TAKETO
KAJINAMI HITOSHI
SUZUKI YASUYUKI

(54) SOLID-STATE IMAGE PICKUP DEVICE

(57)Abstract:

PROBLEM TO BE SOLVED: To obtain a solid-state image pickup device which enables the miniaturization of an image pickup unit and is capable of additionally reducing the diameter at the front end of an electronic endoscope, etc.

SOLUTION: Bonding pads 25 disposed at the outer peripheral part of a solid-state image pickup chip 18 and bonding pads 26 disposed at a perpendicularly facing substrate 20a bonded to the rear surface of the solid-state image pickup chip 18 are connected by a connecting means 29 consisting of a film formed with wiring patterns. The rear surface of the substrate 20a is joined with a horizontally facing substrate 20b. Electronic parts 19 are packaged to the stepped surface of the substrate 20b recessed from the substrate 20 and signal cable 30 are connected to the terminal parts 27 formed at the end of the stepped surface of the substrate 20b. As a result, the substrate 20 and 20b, the electronic parts 19 packaged at the substrate 20b and the terminal parts 27 of the signal cables are housed within the projection area of the solid-state image pickup chip 18.

